

SELECTIVE POLISHING WITH SLURRIES

CONTAINING POLYELECTROLYTES

ABSTRACT OF THE DISCLOSURE

5 Polishing rate selectivity is increased by providing a polyelectrolyte in the polishing slurry. The polishing selectivity of silicon oxide to silicon nitride is enhanced by using an anionic polyelectrolyte. The polishing selectivity of metals to silicon oxide, silicon nitride and/or silicon oxynitride is increased by using a cationic polyelectrolyte.